



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-01-17
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	NICOULEAU	Representative title	APMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement	
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Legal statement	
Supplier acceptance*	true Legal declaration* Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.	

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
TSB512IDT	1DO7A239CE6	A	64BA-BO2A	2025-01-17
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	76.50	mg	Each	ECOPACK® 3
Identity	Authority			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
1	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Tin (Sn), matte	Copper Alloy	0

Package designator	Package size	Number of instances	Shape
DSO	4.8x3.8	8	gull wing
Comment			
Comment	O7 SO 08.15JEDEC		

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false

Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false

Exemption Id.	Description

QueryList : California Prop65 list, dated 17th Nov 2023	Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen	true
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen	false

Substance	amount in product (mg)	Application	ppm in product
Nickel	0.000	alloy	0

QueryList - Customer	Response
QUERY	Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014	Response
QUERY	Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products	false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products	false

Hazardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
O	O	O	O	O

QueryList : REACH-7th November 2024	Response
QUERY	Response

1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH					true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product	
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH					true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article / Homogeneous material	



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Tin,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	true
All the adhesive impacted complies with GB 33372	true

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	False

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	1D07*A239CE6		76.5000		6000002.0	1000000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	2.106	mg	supplier	die	Silicon(Si)	7440-21-3		2.069	mg	982431	27046
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.005	mg	2374	65
				supplier	passivation	Silicon oxide	7631-86-9		0.032	mg	15195	418
Leadframe	M-004 Copper and its alloys	30.514	mg	supplier	alloy	Copper(Cu)	7440-50-8		29.125	mg	954480	380719
				supplier	alloy	Iron(Fe)	7439-89-6		0.685	mg	22449	8954
				supplier	alloy	Iron phosphide	1310-43-6		0.041	mg	1344	536
				supplier	alloy	Zinc(Zn)	7440-66-6		0.036	mg	1180	471
				supplier	metallization	Silver(Ag)	7440-22-4		0.627	mg	20548	8196
Die attach	M-011 Other inorganic materials	0.301	mg	supplier	glue	Silver(Ag)	7440-22-4		0.265	mg	880399	3464
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.015	mg	49834	196
				supplier	glue	Isobornyl acrylate	5888-33-5		0.015	mg	49834	196
				supplier	glue	Methyl acrylate polymer	87320-05-6		0.006	mg	19934	78
Bonding wires	M-004 Copper and its alloys	0.049	mg	supplier	wire	Copper(Cu)	7440-50-8		0.049	mg	1000000	641
Encapsulation	M-011 Other inorganic materials	42.812	mg	supplier	mold compound	Silica vitreous	60676-86-0		30.653	mg	715991	400693
				supplier	mold compound	Silicon oxide	7631-86-9		6.422	mg	150005	83948
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		3.211	mg	75002	41974
				supplier	mold compound	Phenol resin	26834-02-6		2.141	mg	50009	27987
				supplier	mold compound	Carbon black	1333-86-4		0.214	mg	4999	2797
				supplier	mold compound	Bismuth compound	7440-69-9		0.171	mg	3994	2235
Connections coating	Solder	0.718	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		0.718	mg	1000000	9386